Electronic Patent Application Fee Transmittal								
Application Number:	10666930							
Filing Date:	19-Sep-2003							
Title of Invention:	Method and apparatus for supporting wafers for die singulation and subsequent handling							
First Named Inventor/Applicant Name:	Warren M. Farnworth							
Filer:	Jason Nixon/Sharley Thayne							
Attorney Docket Number:	2269-5529US (02-0766.00/U							
Filed as Large Entity								
Utility Filing Fees								
Description	Description		Quantity	Amount	Sub-Total in USD(\$)			
Basic Filing:								
Pages:								
Claims:								
Miscellaneous-Filing:								
Petition:								
Patent-Appeals-and-Interference:								
Post-Allowance-and-Post-Issuance:								
Extension-of-Time:								

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
	Tota	O (\$)	180	